

II. CLAIM AMENDMENTS

1. (currently amended) Process for forming a thermal print head die module having a bonded pair of substrates comprising the steps of applying a thin coating of a heat-curable, photopatternable epoxy polymer composition to a lower heater substrate; drying said coating to form a semi-solid adhesive layer; photoexposing said semi-solid adhesive layer, through a mask, polishing said semi-solid adhesive layer and developing passageways therethrough, to form a patterned adhesive fluidic ink passageway epoxy layer; pressing said patterned adhesive layer and supporting lower substrate against the surface of an upper ink inlet substrate to bond said adhesive layer to said substrates and form a bonded pair of substrates.
2. (original) Process of claim 1 wherein one of the two substrates is a microelectronic wafer containing multiple die sites, each die of which contains electronic circuitry.
3. (original) Process of claim 2 wherein the bonded pair of substrates is subsequently singulated into individual microfluidic devices.
4. (cancelled)